

Configurable Four Output, Low Jitter Clock Generator for Automotive

Features

- AEC-Q100 Automotive Qualified
- Low RMS Phase Jitter: <1 ps (typ.)
- Complies with PCIe Gen1/2/3/4 Common Clock Spec
- High Stability: ±25 ppm, ±50 ppm
- Wide Temperature Range:
 - Automotive Grade 2: –40°C to +105°C
- Automotive Grade 3: -40°C to +85°C
- High Supply Noise Rejection: -50 dBc
- Four Format-Configurable Outputs:
 LVPECL, LVDS, HCSL, LVCMOS
- Available Pin-Selectable Frequency Table
 - 1 Pin per Bank for 2 Frequency Sets
- Wide Frequency Range:
 - 2.3 MHz 460 MHz
- 20-Pin QFN Footprint (5.0 mm x 3.2 mm)
- · Excellent Shock and Vibration Immunity
- High Reliability
 - 20x better MTF than quartz-based devices
- Wide Supply Range of 2.25V to 3.6V
- Lead Free and RoHS-Compliant

Applications

- Automotive Infotainment
- Automotive ADAS
- Autonomous Driving
- · In-Vehicle Network

General Description

The DSA400 is a four output clock generator. It utilizes proven PureSilicon[™] MEMS technology to provide excellent jitter and stability while incorporating additional device functionality.

The nominal frequencies of the outputs can be identical or independently derived from common PLLs.

The four output DSA400 MEMS oscillators are excellent choices for use as clock references in automotive applications in which small size, low power consumption, and long-term reliability are paramount. The DSA400 is AEC-Q100 qualified.

Each output may be configured independently to support a single-ended LVCMOS interface or a differential interface. Differential options include LVPECL, LVDS, or HCSL.

The DSA400 provides two independent select lines for choosing between two sets of pre-configured frequencies per bank. It also has two OE pins to allow for enabling and disabling outputs.

The DSA400 is packaged in a 20-pin QFN (5 mm x 3.2 mm) and is available in extended commercial and industrial temperature grades.

The DSA400 is a highly configurable device and is factory programmed to meet the customer's needs. Microchip's ClockWorks Configurator must be used to choose the necessary options, create the final part number, data sheet, and order samples.

Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage	
Input Voltage	–0.3V to V _{DD} +0.3V
ESD Protection (HBM)	
ESD Protection (MM)	
ESD Protection (CDM)	

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
Supply Voltage (Note 1)	V _{DD}	2.25		3.6	V	—
Core Supply Current (Note 2)	IDDCORE	_	40	44	mA	OE(1:2) = 0. All outputs disabled.
Frequency Stability	Δf	_		±25	2222	All temperature and V _{DD}
Frequency Stability	Δι	—	_	±50	ppm	ranges.
Aging - First Year	Δf_{Y1}	—	_	±5	ppm	One year at +25°C
Aging - After First Year	Δf_{Y2} +	_	_	<±1	ppm/yr	Year two and beyond at +25°C
Start-up Time (Note 3)	t _{SU}	_	_	5	ms	T = +25°C
	V _{IH}	0.75 x V _{DD}			V	Input logic high
Input Logic Levels	V _{IL}			0.25 x V _{DD}	v	Input logic low
Output Disable Time (Note 4)	t _{DA}	_		5	ns	OE(1:2) transition from 1 to 0
Output Enable Time (Note 4)	t _{EN}	_	_	20	ns	OE(1:2) transition from 0 to 1
Pull-Up Resistor	R _{PU}	_	40	_	kΩ	All input pins have an internal pull-up

Electrical Charcteristics: V_{DD} = 3.3V; T_A = +25°C unless otherwise specified.

Note 1: V_{DD} pins should be filtered with a 0.1 μ F capacitor connected between V_{DD} and V_{SS} .

2: The addition of I_{DDCORE} and I_{DDIO} provides the total current consumption of the device.

3: t_{SU} is time to 100 ppm stable output frequency after V_{DD} is applied and outputs are enabled.

4: See the Output Waveform section for more information.

TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
Temperature Ranges	1			I		I
	T _A	-40		+105	°C	Ordering Option L
Operating Temperature Range (T)	T _A	-40	_	+85	°C	Ordering Option I
Junction Temperature	Τ _J	_	_	+150	°C	—
Storage Temperature Range	Τ _S	-40	_	+150	°C	—
Soldering Temperature	_		_	+260	°C	40 sec. max.

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature, and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above +150°C can impact the device reliability.

2.0 PIN DESCRIPTIONS



FIGURE 2-1: Pin Configuration, 20-Pin QFN (5.0 mm x 3.2 mm)

The descriptions of the pins are listed in Table 2-1.

Pin Number	Pin Name	Pin Type	Description
1	OE1	I	Output Enable for Bank1 (CLK0 and CLK3); Active-High. See Table 3-1.
2	NC	N/A	Leave unconnected or connect to ground.
3	V _{SS}	PWR	Ground.
4	V _{SS}	PWR	Ground.
5	CLK0-	0	Complement output of differential pair 0 (off when in LVCMOS format).
6	CLK0+	0	True output of differential pair 0 or LVCMOS output 0.
7	CLK1–	0	Complement output of differential pair 1 (off when in LVCMOS format).
8	CLK1+	0	True output of differential pair 1 or LVCMOS output 1.
9	V _{DD2}	PWR	Power Supply for Bank2 (CLK1 and CLK2).
10	FSB2	I	Input for selecting pre-configured frequencies on Bank2 (CLK1 and CLK2).
11	OE2	I	Output Enable for Bank2 (CLK1 and CLK2); Active-High. See Table 3-1.
12	NC	N/A	Leave unconnected or connect to ground.
13	V _{SS}	PWR	Ground.
14	V _{SS}	PWR	Ground.
15	CLK2–	0	Complement output of differential pair 2 (off when in LVCMOS format).
16	CLK2+	0	True output of differential pair 2 or LVCMOS output 2.
17	CLK3–	0	Complement output of differential pair 3 (off when in LVCMOS format).
18	CLK3+	0	True output of differential pair 3 or LVCMOS output 3.
19	V _{DD1}	PWR	Power Supply for Bank1 (CLK0 and CLK3).
20	FSB1	I	Input for selecting pre-configured frequencies on Bank1 (CLK0 and CLK3).

TABLE 2-1:	PIN FUNCTION TABLE

3.0 OPERATIONAL DESCRIPTION

The DSA400 is a clock generator. Unlike older clock generators in the industry, it does not require an external crystal to operate; it relies on the integrated MEMS resonator that interfaces with internal PLLs. This technology enhances performance and reliability by allowing tighter frequency stability over a far wider temperature range. In addition, the higher resistance to shock and vibration decreases the aging rate to allow for much improved product life in the system.

3.1 Inputs

There are four input signals in the device. Each has an internal (40 k Ω) pull-up to default the selection to a high (1). Inputs can be controlled through hardware strapping method with a resistor to ground to assert the input low (0). Inputs may also be controlled by other components' GPIOs

In case more than one frequency set is desired, FSB1 and FSB2 are used to independently select one of two sets per bank. FSB1 selects the pre-configured set on Bank1 (CLK0 and CLK3) and FSB2 selects the pre-configured set on Bank2 (CLK1 and CLK2), as shown in Table 0-1 in the Product Identification System section.

If there is a requirement to disable outputs, the inputs OE1 and OE2 are used in conjunction to disable the banks of outputs. Outputs are disabled in tri-state (Hi-Z) mode. See Table 3-1 for more information.

TABLE 3-1:OUTPUT ENABLESELECTION TABLE

OE1	OE2	Bank 1 (CLK0 & CLK3)	Bank 2 (CLK1 & CLK2)
0	0	Hi-Z	Hi-Z
0	1	Hi-Z	Running
1	0	Running	Hi-Z
1	1	Running	Running

3.2 Outputs

The four outputs are grouped into two banks. Each bank is supplied by an independent V_{DD} to allow for optimized noise isolation between the two banks. Each bank provides two synchronous outputs generated by a common PLL:

- · Bank1 is composed of outputs CLK0 and CLK3.
- Bank2 is composed of outputs CLK1 and CLK2.

Each output may be pre-configured independently to be one of the following formats: LVCMOS, LVDS, LVPECL or HCSL. In case the output is configured to be single-ended LVCMOS, the frequency is generated on the true output (CLKx+) and the complement output (CLKx-) is shut off in a low state. Frequencies can be chosen from 2.3 MHz to 460 MHz for differential outputs and from 2.3 MHz to 170 MHz on LVCMOS outputs.

3.3 Power

 V_{DD1} and V_{DD2} supply the power to banks 1 and 2 respectively. Each V_{DD} may have a different supply voltage from the other as long as it is within the 2.25V to 3.6V range. Each V_{DD} pin should have a 0.1 μF capacitor to filter high-frequency noise. V_{SS} is common to the entire device.

4.0 TERMINATION SCHEMES

4.1 LVPECL



Parameter	Symbol	Min.	Тур.	Max.	Units	Condition		
Output Logic	V _{OH}	V _{DD} – 1.08		_	v	Output Logic High, $R_L = 50\Omega$ to V_{DD} -2V		
Levels	V _{OL}	—	—	V _{DD} – 1.55	v	Output Logic Low, $R_L = 50\Omega$ to V_{DD} -2V		
Peak-to-Peak Output Swing	—	_	800	—	mV	Single-Ended		
Output Transition Time	t _R	_	250	—	50	Rise Time. 20% to 80%; $R_L = 50\Omega$ to V_{DD} -2V		
(Note 2)	t _F	_	250	—	ps	Fall Time. 20% to 80%; R _L = 50 Ω to V _{DD} -2V		
Frequency	f ₀	2.3	_	460	MHz	Single Frequency		
Output Duty Cycle	SYM	48	_	52	%	Differential		
IO Supply Current (Note 3)	I _{DDIO}	_	35	38	mA	Per Output at 125 MHz		
Period Jitter (Note 4)	J _{PER}	_	2.5	_	ps _{RMS}	CLK(0:3) = 156.25 MHz		
		_	0.25	_		200 kHz to 20 MHz @ 156.25 MHz		
Integrated Phase Noise	J _{PH}		0.38		ps _{RMS}	100 kHz to 20 MHz @ 156.25 MHz		
			1.7	2		12 kHz to 20 MHz @ 156.25 MHz		

TABLE 4-1: LVPECL OUTPUTS (Note 1)

Note 1: LVPECL applicable to automotive Grade 3 temperature only.

2: See the Output Waveform section for more information.

3: The addition of I_{DDCORE} and I_{DDIO} provides the total current consumption of the device.

4: Period jitter includes crosstalk from adjacent output.

4.2 LVDS



FIGURE 4-2: Typical LVDS Termination Scheme.

If the 100Ω clamping resistor does not exist inside the receiving device, it should be added externally on the PCB and placed as close as possible to the receiver.

Parameter	Symbol	Min.	Тур.	Max.	Units	Condition
Output Offset Voltage	V _{OS}	1.125	_	1.46	V	R = 100Ω Differential
Delta Offset Voltage	ΔV_{OS}	_	_	100	mV	—
Peak-to-Peak Output Swing	V _{PP}	_	350	_	mV	Single-Ended
Output Transition Time	t _R	_	200	_		Rise Time, 20% to 80%, R _L = 50 Ω , C _L = 2 pF
(Note 1)	t _F	_	200	_	ps	Fall Time, 20% to 80%, R_L = 50 Ω , C_L = 2 pF
Frequency	f ₀	2.3		460	MHz	Single Frequency
Output Duty Cycle	SYM	48	_	52	%	Differential
IO Supply Current (Note 2)	I _{DDIO}	_	9	12	mA	Per Output at 125 MHz
Period Jitter	J _{PER}	—	2.5	—	ps _{RMS}	—
Integrated Phase Noise			0.28	_		200 kHz to 20 MHz @ 156.25 MHz
	J _{PH}		0.4	_	ps _{RMS}	100 kHz to 20 MHz @ 156.25 MHz
Note 1: See th		_	1.7	2.0		12 kHz to 20 MHz @156.25 MHz

TABLE 4-2: LVDS OUTPUTS

Note 1: See the Output Waveform section for more information.

2: The addition of I_{DDCORE} and I_{DDIO} provides the total current consumption of the device.

4.3 HCSL



FIGURE 4-3:	Typical HCSL Termination Scheme.

The 33Ω series resistors are needed to avoid excessive ringing.

Parameter	Symbol	Min.	Тур.	Max.	Units	Condition
Output Logic	V _{OH}	0.725			v	Output Logic High, $R_L = 50\Omega$
Levels	V _{OL}	_	_	0.1		Output Logic Low, $R_L = 50\Omega$
Peak-to-Peak Output Swing	_	_	750		mV	Single-Ended
Output Transition Time	t _R	200	_	400		Rise Time, 20% to 80%, R_L = 50 Ω , C_L = 2 pF
(Note 1)	t _F	200	_	400	– ps	Fall Time, 20% to 80%, R _L = 50Ω, C _L = 2 pF
Frequency	f ₀	2.3	—	460	MHz	Single Frequency
Output Duty Cycle	SYM	48	_	52	%	Differential
IO Supply Current (Note 2)	I _{DDIO}	_	20	22	mA	Per Output at 125 MHz.
Period Jitter	J _{PER}		2.5	_	ps _{RMS}	—
			0.25	_		200 kHz to 20 MHz @ 156.25 MHz
Integrated Phase Noise	J _{PH}		0.37		ps _{RMS}	100 kHz to 20 MHz @ 156.25 MHz
Note 1: See th		_	1.7	2.0		12 kHz to 20 MHz @156.25 MHz

TABLE 4-3: HCSL OUTPUTS

Note 1: See the Output Waveform section for more information.

2: The addition of I_{DDCORE} and I_{DDIO} provides the total current consumption of the device.

4.4 LVCMOS



FIGURE 4-4: Typical LVCMOS Termination Scheme.

The 27 Ω Series resistor complements the output impedance of about 23 Ω to 50 Ω impedance to match the line 50 Ω characteristic impedance to prevent reflections from the driver back to the receiver.

Parameter	Symbol	Min.	Тур.	Max.	Units	Condition
Output Logic	V _{OH}	0.9 x V _{DD}			v	Output Logic High, I = ±6 mA
Levels	V _{OL}		—	0.1 x V _{DD}		Output Logic Low, I = ±6 mA
Output	t _R		1.1	2.0		Rise Time, 20% to 80%, C _L = 15 pF
Transition Time (Note 1)	t _F	—	1.3	2.0	ns	Fall Time, 20% to 80%, C _L = 15 pF
Frequency	f ₀			100	MHz	—
Output Duty Cycle	SYM	44	_	55	%	_
IO Supply Current (Note 2)	I _{DDIO}	_	11	14	mA	Per Output at 125 MHz, C _L = 15 pF
Period Jitter	J _{PER}		3	_	ps _{RMS}	CLK(0:3) = 125 MHz
			0.3	_		200 kHz to 20 MHz @ 125 MHz
Integrated Phase Noise	J _{PH}	_	0.38	_	ps _{RMS}	100 kHz to 20 MHz @ 125 MHz
1 11030 110130		_	1.7	2.0		12 kHz to 20 MHz @125 MHz

TABLE 4-4: LVCMOS OUTPUTS

Note 1: See the Output Waveform section for more information.

2: The addition of I_{DDCORE} and I_{DDIO} provides the total current consumption of the device.

5.0 OUTPUT WAVEFORM



FIGURE 5-1: Differential Output (LVDS, LVPECL, HCSL).





6.0 CONNECTION DIAGRAM

The connection diagram below includes recommended capacitors to be placed on each V_{DD} for noise filtering.



FIGURE 6-1: DSA400 Connection Diagram.

7.0 SOLDER REFLOW PROFILE



MSL 1 @ 260°C refer to JSTD-020C					
Ramp-Up Rate (200°C to Peak Temp)	3°C/sec. max.				
Preheat Time 150°C to 200°C	60-180 sec.				
Time Maintained above 217°C	60-150 sec.				
Peak Temperature	255°C to 260°C				
Time within 5°C of Actual Peak	20-40 sec.				
Ramp-Down Rate	6°C/sec. max.				
Time 25°C to Peak Temperature	8 minutes max.				

8.0 PACKAGING INFORMATION

8.1 Package Marking Information



Legenc	Y YY WW NNN @3 *	Product code or customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.					
Note:	In the event the full Microchip part number cannot be marked on one line, it w be carried over to the next line, thus limiting the number of availabl characters for customer-specific information. Package may or may not include the corporate logo. Underbar (_) and/or Overbar (⁻) symbol may not be to scale.						
1							



20-Lead QFN 5.0 mm x 3.2 mm Package Outline and Recommended Land Pattern

APPENDIX A: REVISION HISTORY

Revision A (June 2020)

Initial release of DSA400 as Microchip data sheet DS20006356A.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

	X CLK3 Output		put Ou	X LK1 Itput	X CLK0 Output	Qxxxx Freq. Code	<u>X</u> │ Package	e Te	X mp. nge		<u>x</u> bility	X Pack		XXX Automot Suffix	- tive		
Device:	Format	-	-		Format	l our littor		Exa	mple	es:							
Device:	DSA4	50:	Clock C		Four Output, tor	Low Jiller		a)		DSA400-2143QxxxxKI1VAO:							
CLK3 Output Format:	0 1 2 3 4		OFF LVCMOS LVPECL LVDS HCSL						LVI CL Ter	Configurable Four Output, Low Jitter Clock Generator; LVPECL CLK3; LVCMOS CLK2; HCSL CLK1; LVDS CLK0; Frequency Code; 20-Pin QFN; –40°C to +85°C Temp. Range; ±50 ppm Stability; 72/Tube; Standard automotive							
CLK2 Output Format:	1 2 3 4	= = =	LVCMOS LVPECL LVDS HCSL					b)	DSA400-4132QxxxKI2TVAO: Configurable Four Output, Low Jitter Clock Generator; HCSL CLK3; LVCMOS CLK2; LVDS CLK1; LVPECL CLK0; Frequency Code; 20-Pin QFN; -40°C to +85°C Temp. Range; ±25 ppm Stability;						LK1; LVPECL		
CLK1 Output Format:	0 1 2 3 4	= = = =	OFF LVCMOS LVPECL LVDS HCSL					c)	DS/ Co	I,000/Reel; Standard automotive SA400-0303QxxxxKL2VAO: Configurable Four Output, Low Jitter Clock Genera DFF CLK3; LVDS CLK2; OFF CLK1; LVDS CLK0; F							
CLK0 Output Format:	1 2 3 4	= = =	LVCMOS LVPECL LVDS HCSL						Ra	quency Code; 20-Pin QFN; -40°C to +105°C Temp. Range; ±25 ppm Stability; 72/Tube; Standard automotive							
Frequency Code	: Qxxxx	=			igned by the section for			d)	 DSA400-1111QxxxxKL1TVAO: Configurable Four Output, Low Jitter Clock Gene LVCMOS CLK3 through CLK0; 				ock Generator;				
Package:	к	=	20-Pin QI	FN					Frequency Code; 20-Pin QFN; –40°C to +105°C Te Range; ±50 ppm Stability; 1,000/Reel; Standard automotive) +105°C Temp.			
Temperature Range:	L I	= =			C (Automotiv (Automotive)	No	te 1:	Tape and Reel identifier only appears in the							
Stability:	1 2	= =	±50 ppm ±25 ppm							catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.							
Packing:	Blank T	= =	72/Tube 1,000/Re	el					ומףכ מות הכבו טאנטוו.								
Automotive Suff	fix: VXX = Automotive Suffix in which "XX" is assigned by Microchip. Default value is "AO" for standard automo- tive part																

Factory Configuration Code Assignment of Qxxxx

The DSC400 is meant for customers to define their own frequency requirements at the four available outputs using ClockWorks Configurator. The Qxxxx number identifies these specific customer requirements and is assigned by the factory.

	Outputo	FS	Qxxxx Number			
Bonkt	Outputs	1 (default)	0			
Bank1	CLK0	CLK0 125 MHz 150				
	CLK3	50 MHz	25 MHz			
	Outpute	FS	Q1234			
Bank2	Outputs	1 (default)	0	1		
DdllKZ	CLK1	156.25 MHz	100 MHz			
	CLK2	156.25 MHz	100 MHz			

TABLE 0-1:EXAMPLE OF HOW FSB1 & FSB2 ARE APPLIED & THE QXXXX ASSIGNMENT

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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